

Mask Set Errata

MSE9S12D128_1L40K
Rev 0.0, 03/2003

Mask Set Errata for
MC9S12DT128
Mask 1L40K



Introduction

This errata provides information applicable to the following MCU mask sets for the MC9S12DT128/DJ128 and DG128 devices:

- 1L40K*

**Note that the MC9S12DB128 is not available in the 1L40K mask.*

MCU Device Mask Set Identification

The mask set is identified by a four-character code consisting of a letter, two numerical digits, and a letter, for example F74B. Slight variations to the mask set identification code may result in an optional numerical digit preceding the standard four-character code, for example 0F74B.

MCU Device Date Codes

Device markings indicate the week of manufacture and the mask set used. The data is coded as four numerical digits where the first two digits indicate the year and the last two digits indicate the work week. The date code "9115" would indicate the 15th week of the year 1991.

MCU Device Part Number Prefixes

Some MCU samples and devices are marked with an SC, PC, ZC or XC prefix. An SC, PC or ZC prefix denotes special/custom device. An XC prefix denotes device is tested but is not fully characterized or qualified over the full range of normal manufacturing process variations. After full characterization and qualification, devices will be marked with the MC prefix.

Errata System Tracking Numbers

MUCTS00xxx is the tracking number for device errata. It can be used with the mask set and date code to identify a specific errata to a Motorola representative.

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ERRATA SUMMARY

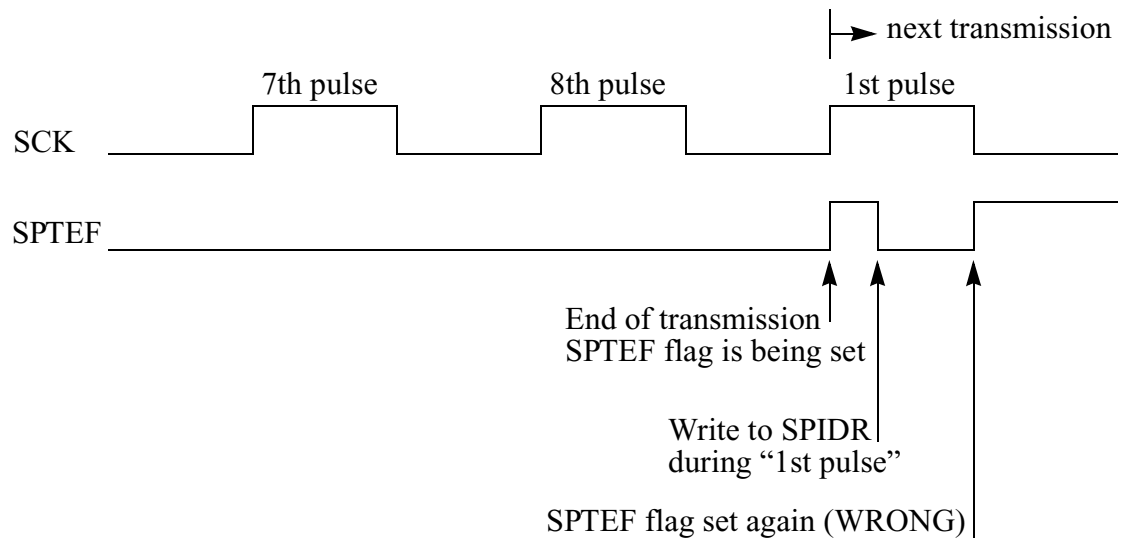
Errata Number	Module affected	Brief description
MUCts00708	SPI	SPTEF flag set wrongly
MUCts00735	ATD	Flags in ATDSTAT0 do not clear by writing "1", ETORF sets wrongly
MUCts00742	SPI	SPI in mode fault state, but MISO output buffer not disabled
MUCts00755	BDM	ACK conflict exiting STOP
MUCts00756	MSCAN	Glitch filter exceeds spec limits
MUCts00757	KWU	Glitch filter exceeds upper 10µs limit
MUCts00778	BYTEFLIGHT	Tx messages of same ID block subsequent lower priority IDs
MUCts00784	ATD	Write to ATDCTL5 may not clear SCF, CCF and ASCIF flags
MUCts00788	PADS	ESD fails at 2KV HBM
MUCts00793	BYTEFLIGHT	FIFO may overflow as RCVFIF is not asserted again
MUCts00799	SPI	MISO not kept after sixteenth SCK edge
MUCts00821	CRG PLL	If osc_clock is 2 to 3 times pll_clock, STOP can cause SCM or reset
MUCts00833	EEPROM	Cumulative EEPROM W/E Cycle Limit For 'V' & 'M' Rated Products

SPTEF flag set wrongly
Errata Number: MUCts00708
Description

When the SPI is enabled in master mode, with the CPHA bit set, back to back transmissions are possible.

When a transmission completes and a further byte is available in the SPI Data Register, the second transmission begins directly after the "minimum trailing time".

The problem occurs when, after the SPTEF flag has been set, a further byte is written into the SPI Data Register during the "1st pulse" of a subsequent transmission.



Then the SPTEF flag is set at the falling SCK edge of the “1st pulse” and data is transferred from the SPI Data Register to the transmit shift register. The result is that the transmission is corrupted and data is lost.

Workaround

After the SPTEF flag has been set, a delay of 1/2 SCK period has to be added before storing data into the SPI Data Register.

ATD: Flags in ATDSTAT0 do not clear by writing ‘1’, ETORF sets wrongly Errata Number: MUCts00735

Description

For the flags SCF, ETORF and FIFOR in ATDSTAT0 it is specified that writing a ‘1’ to the respective flag clears it. This does not work. Writing ‘1’ to the respective flag has no effect. The ETORF flag is also set by a non-active edge, e.g. falling edge trigger (ETRILE=0, ETRIGP=0). ETORF is set on both falling edges and rising edges while conversion is in progress.

Workaround

SCF

1. Use the alternative flag clearing mechanisms:
 - a. Write to ATDCTL5 (a new conversion sequence is started)
 - b. If AFFC=1 a result register is read

ETORF

1. Use the alternative flag clearing mechanisms:

- a. Write to ATDCTL2, ATDCTL3 or ATDCTL4 (a conversion sequence is aborted)
- b. Write to ATDCTL5 (a new conversion sequence is started)
2. Avoid external trigger edges during conversion process by using short pulses
3. Ignore ETROF flag

FIFOR

1. Use the alternative flag clearing mechanism:
 - a. Start a new conversion sequence (write to ATDCTL5 or external trigger)

SPI: SPI in Mode Fault state, but MISO output buffer not disabled**Errata Number: MUCts00742****Description**

When the SPI is in Mode Fault state (MODF flag set), according to the specification, all SPI output buffers (SS, SCK, MOSI, MISO) should be disabled. However, the MISO output buffer is not disabled.

Workaround

None

BDM: ACK conflict exiting STOP**Errata Number: MUCts00755****Description**

When using the Background Debugger to debug code which contains STOP instructions, the host debugger can lose clock sync with the target device. If the ACK protocol is enabled, a target command which is expecting to send an ACK pulse can conflict with a host issued SYNC command attempting to re-establish clock sync between the host and target.

Workaround

The ACK protocol can be disabled when debugging source code which contains STOP instructions. The host SYNC command may then be used to re-establish clock sync between the host and target after a STOP instruction.

MSCAN: Glitch filter exceeds spec limits**Errata Number: MUCts00756****Description**

The specified MSCAN wake-up glitch filter pulse limits can be exceeded. At low temp/high VDD the module may wake up from sleep mode on glitches $<2\mu\text{s}$ while for pulses $>5\mu\text{s}$ it may not wake up from sleep mode at high temp/low

VDD. The device operates at relaxed limits: MSCAN Wake-up dominant pulse filtered: max. 1 μ s MSCAN Wake-up dominant pulse pass: min. 7 μ s

Workaround None

Key wake-up: Glitch filter exceeds upper 10 μ s limit **Errata Number: MUCts00757**

Description The specified maximum limit of the key wake-up glitch filter pulse can be exceeded at high temp/low VDD, i.e. the CPU may not wake up from STOP mode on pulses $\geq 10\mu$ s. The device operates at a relaxed limit of 14 μ s.

Workaround None

BYTEFLIGHT: Tx messages of same ID block subsequent lower priority IDs
Errata Number: MUCts00778

Description If there are two or more buffers set up with the same identifier, message transmission takes place until the first message of the same ID messages has been sent. All subsequent messages with lower priority are blocked from being transmitted in the same communication cycle.

Workaround None

ATD: Write to ATDCTL5 may not clear SCF, CCF and ASCIF flags
Errata Number: MUCts00784

Description If a write to ATDCTL5 happens at exactly the bus cycle where an ongoing conversion sequence ends, the SCF, CCF and (if ASCIE=1) ASCIF flags remain set and are NOT cleared by a write to ATDCTL5.

Workaround 1. Make sure the device is protected from interrupts (temporarily disable interrupts with the I mask bit).
2. Write to ATDCTL5 twice.

ESD fails for 2KV HBM**Errata Number: MUCts00788**

Description ESD performance:

- 2KV HBM (Human Body Model) fails ESD tests
- 1.75KV HBM pass ESD tests

Therefore, reduced ESD spec for HBM is 1.75KV

Workaround None

Byteflight: FIFO may overflow as RCVFIF is not asserted again**Errata Number: MUCts00793**

Description If the last message in the FIFO is read, i.e. buffer 0 is unlocked around the end of a new incoming FIFO message, the FIFO not empty (RCVFIF) flag is not asserted again. This will eventually result in a FIFO overflow. The time window is about 6 osc clock cycles in which the two events must occur to cause the problem.

Workaround None

SPI: MISO not kept after sixteenth SCK edge**Errata Number: MUCts00799**

Description In SPI slave mode with CPHA set, MISO can change falsely after a transmission, two to three bus clock cycles after the sixteenth SCK edge. This can lead to a hold time violation on the SPI master side.

Workaround There are two possible workarounds for this problem:

1. Decrease the bus clock of the slave SPI to satisfy the “Masters MISO Hold Time”.
 $T_{bus}(Slave) \geq 0.5 * \text{“Masters MISO Hold Time”}$
2. Software workaround:
 The slave has to transmit a dummy byte after each data byte, which must fulfill the following requirements:
 - The dummy bytes first bit to be transmitted (depending on LSBFE bit) must be equal to the last bit of the data byte transmitted before.
 The dummy byte has to be stored into SPIDR during the transmission of the corresponding data byte.

- MISO does not change after the data byte.
- The Master has to receive two bytes, the data byte and the dummy byte.
 - Master receives the data byte correctly and has to skip the dummy byte.

PLL: If osc_clock is 2 to 3 times pll_clock, STOP can cause SCM or reset
Errata Number: MUCts00821

Description

This Erratum applies only to systems where PLL is used to divide down the osc_clock by a ratio between 2 and 3. If

1. pll_clock (PLLON=1) is running and
2. $2 < \text{osc_clock} \div \text{pll_clock} < 3$ and
3. Full stop mode is entered (STOP instruction with PSTP Bit =0)

there is a small possibility that when entering full stop mode the chip reacts as follows:

1. If self clock mode is disabled (SCME=0) a clock monitor reset will occur. The system does NOT enter full stop mode.
2. If self clock mode and SCM interrupt are enabled (SCME=1 and SCMIE=1) a self clock mode interrupt is generated. The SCMIF flag is set. The system does NOT enter full stop mode.
3. If self clock mode is enabled and SCM interrupt is disabled (SCME=1 and SCMIE=0) the system will enter full stop mode. However, after wakeup, self clock mode is immediately entered without performing the specified clock quality check. The SCMIF flag will be set.

Workaround

1. Avoid osc_clock \div pll_clock ratios between 2 and 3.
2. If a osc_clock \div pll_clock ratio between 2 and 3 is required, perform the following before entering full stop mode.
 - a. Deselect PLL (PLLSEL=0)
 - b. Turn off PLL (PLLON=0)
 - c. Enter stop
 - d. On exit from stop, turn on PLL again (PLLON=1)

Cumulative EEPROM W/E Cycle Limit For 'V' & 'M' Rated Products

Errata Number: MUCts00833

Description

The EEPROM charge pump capabilities limit the cumulative number of sector Program/Erase cycles at temperatures greater or equal to 105°C ambient. 'C' temperature rated (85°C) products are not affected by this errata. EEPROM Program/Erase cycling is therefore bounded by the following 2 criteria.

1. Any single byte or sector cannot exceed the specification of 100K Program/Erase cycles as noted by the following:

		Min	Typ	Max	
EEPROM number of Program/Erase cycles: ($-40^{\circ}\text{C} \leq T_j \leq 0^{\circ}\text{C}$)	n_{EEPE}	10,000			Cycles
EEPROM number of Program/Erase cycles: ($0^{\circ}\text{C} \leq T_j \leq 140^{\circ}\text{C}$)	n_{EEPE}	100,000			Cycles

2. The cumulative number of sector Program/Erase cycles is bounded as noted below:

		Min	Typ	Max	
EEPROM number of sector cumulative Program/Erase cycles	125°C (M) 105°C (V) 85°C (C)	n_{MAX}	20.0M 30.0M 51.2M ⁽¹⁾		Cycles

1. Note that 51.2M sector cycles is equivalent to 100,000 full array (2048 bytes = 512 sectors) cycles as commonly specified.

Although the charge pump limits the cumulative number of Program/Erase cycles, any portion of the array has high (up to 100K) Program/Erase cycle endurance capability at elevated temperatures as demonstrated in the following examples:

Examples

- MC9S12Dx128 EEPROM has 512 EEPROM sectors (1 sector = 4 Bytes)
- Definitions:

X = Number of sectors $\Leftrightarrow X \leq 512$ sectors

Y = Number of Prog/Erase cycles for all X sectors $\Leftrightarrow Y \leq 100K$ cycs (spec)

X*Y = Cumulative Number of Program/Erase cycles for the X sectors

85°C Temperature, 'C' rated product:

- Capability: Full specification
=> 512 sectors (full array) x 100,000 Cycles ≤ 51.2 M cycles

105°C & 125°C Temperature, 'V' and 'M' rated product:

- Capability: Reduced cumulative number of Program/Erase cycles:

$$\mathbf{125^{\circ}\text{C}:} \quad \sum_{i=1}^n X_i \times Y_i \leq 20\text{M Cycles}$$

$$\mathbf{105^{\circ}\text{C}:} \quad \sum_{i=1}^n X_i \times Y_i \leq 30\text{M Cycles}$$

=> Using the above formula for an application that requires a portion of the EEPROM array at high endurance (up to 100K) and other portions for lesser endurance needs, the following is an example calculation for total cumulative cycles at 125°C:

128 sectors (¼ array) x 100K cycs + 256 sectors (½ array) x 25K cycs + 128 sectors (¼ array) x 1000 cycs < 20M cycles

Workaround

None

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